TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (π -MOSII .5)

2 S K 1 9 2 9

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS.

CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE APPLICATIONS.

• Low Drain-Source ON Resistance : $R_{DS(ON)} = 2.5\Omega$ (Typ.)

• High Forward Transfer Admittance : $|Y_{fs}| = 2.0S$ (Typ.)

• Low Leakage Current : $I_{DSS} = 300 \mu A \text{ (Max.)} \text{ (V}_{DS} = 720 \text{ V)}$

• Enhancement-Mode : $V_{th} = 1.5 \sim 3.5 \text{V} (V_{DS} = 10 \text{V}, I_D = 1 \text{mA})$

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT	
Drain-Source Voltage		$v_{ m DSS}$	900	V	
Drain-Gate Voltage (RGS = $20k\Omega$)		VDGR	900	v	
Gate-Source Voltage		v_{GSS}	±30	v	
Drain Current	DC	${ m I}_{ m D}$	5	A	
Drain Current	Pulse	I_{DP}	15		
Drain Power Dissipation (Tc=25°C)		$P_{\mathbf{D}}$	100	w	
Channel Temperature		$\mathrm{T_{ch}}$	_{th} 150		
Storage Temperature Range		$\mathrm{T_{stg}}$	-55~150	°C	

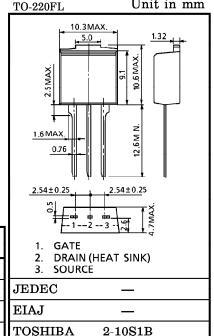
THERMAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	$R_{th(ch-c)}$	1.25	°C/W
Thermal Resistance, Channel to Ambient	R _{th(ch-a)}	83.3	°C/W

THIS TRANSISTOR IS AN ELECTROSTATIC SENSITIVE DEVICE.

PLEASE HANDLE WITH CAUTION.

INDUSTRIAL APPLICATIONS TO-220FL Unit in mm



10.3MAX. 10.3MAX. 10.3MAX. 1. GATE 2. DRAIN (HEAT SINK) 3. SOURCE JEDEC — EIAJ — TOSHIBA 2-10S2B

Unit in mm

Weight: 1.5g

TO-220SM

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ELECTRICAL CHARACTERISTICS (Ta = 25°C)

ELLETHICKE CHARACTERISTICS (Ta = 25 C)								
CHARACT	ERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT	
Gate Leakage C	urrent	IGSS	$V_{GS} = \pm 25V, V_{DS} = 0V$		_	±100	nA	
Drain Cut-off Cu	urrent	$I_{ m DSS}$	$V_{DS} = 720V, V_{GS} = 0V$	_		300	μ A	
Drain-Source Breakdown Volt	V(DD)DGG ID=10mA VGG=0V		900	_	_	V		
Gate Threshold	Voltage	$ m V_{th}$	$V_{ m DS}$ =10V, $I_{ m D}$ =1mA	1.5	_	3.5	V	
Drain-Source ON	N Resistance	R _{DS(ON)}	$V_{ m DS}$ =10V, $I_{ m D}$ =2A	-	2.5	2.8	Ω	
Forward Transfe	er Admittance	$ Y_{fs} $	$V_{ m DS}$ = 20V, $I_{ m D}$ = 2A	1.0	2.0	_	S	
Input Capacitance Ciss			_	700	_			
Reverse Transfer Capacitance		$\mathrm{c}_{\mathrm{rss}}$	$ m V_{DS}$ =25V, $ m V_{GS}$ =0V, $ m f$ =1MHz	_	55	_	pF	
Output Capacitance		C_{OSS}		_	100	<u> </u>		
Switching Time	Rise Time	t_r	$V_{GS} = \begin{bmatrix} 10V & I_D = 2A & V_{OUT} \\ 0V & V_{OUT} \\ & & \\ & & \\ V_{DD} = 400V \\ V_{IN} : t_r, t_f < 5ns, \\ Duty \leq 1\%, t_W = 10\mu s \end{bmatrix}$	_	18	_		
	Turn-on Time	t _{on}		_	30	_		
	Fall Time	t_f		_	12	_	ns	
	Turn-off Time	t_{off}		_	70	_		
Total Gate Charge (Gate-Source Plus Gate-Drain)		$\mathbf{Q}_{\mathbf{g}}$	V _{DD} ≒400V, V _{GS} =10V,	_	60	_	C	
Gate-Source Charge		$\mathbf{Q}_{\mathbf{g}\mathbf{s}}$	$I_{D}=4A$		35	_	nC	
Gate-Drain ("Miller") Charge		$\mathbf{Q}_{\mathbf{gd}}$		_	25	<u> </u>		

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	_	5	A
Pulse Drain Reverse Current	${ m I_{DRP}}$			_	15	Α
Diode Forward Voltage	$v_{ m DSF}$	$I_{DR}=4A, V_{GS}=0V$		_	-1.9	V
Reverse Recovery Time	$ m t_{rr}$	I_{DR} =4A, V_{GS} =0V	_	1000		ns
Reverse Recovered Charge	$Q_{ m rr}$	$dI_{ m DR}$ / dt = 100A / μ s		0.13		μC

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